L Number	Hits	Search Text	DB	Time stamp
1	2	("6348725").PN.	USPAT;	2003/07/18 10:36
	~	(0310723)	US-PGPUB;	2003, 01, 25 20136
			EPO; JPO;	
			DERWENT;	,
			IBM TDB	
2	1671	mem with switch	USPAT.;	2003/07/18 10:37
-			US-PGPUB;	
		•	EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	174	mem with switch and etch\$3 and intermediate	USPAT;	2003/07/18 10:39
	_, •		US-PGPUB;	,,
1			EPO; JPO;	·
			DERWENT;	
			IBM TDB	
4	o	mem with switch and etch\$3 and intermediate	USPAT;	2003/07/18 10:40
		and Tialn	US-PGPUB;	
			EPO; JPO;	1
		,	DERWENT;	ļ.
			IBM TDB	
5	174	intermediate and Tialn	USPAT;	2003/07/18 10:41
			US-PGPUB;	, , , == == , , ,
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
6	. 29	intermediate near33 Tialn	USPAT;	2003/07/18 12:19
_			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	0	sun.in. and li.in. and redeker.in	USPAT;	2003/07/18 12:19
, ·	_		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	14497	sun.in. li.in. and redeker.in	USPAT;	2003/07/18 12:20
			US-PGPUB;	
			EPO; JPO;	
	•		DERWENT;	
			IBM TDB	
9	682	sun.in. and li.in. redeker.in	USPAT;	2003/07/18 12:20
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	52813	sun.in. li.in. redeker.in	USPAT;	2003/07/18 12:20
			US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	1
			IBM_TDB	
11	25	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:21
	1	CMP and amine	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
12	103	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:21
		CMP	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	
13	93	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:21
		CMP and polish\$3	US-PGPUB;	
		• •	EPO; JPO;	
			DERWENT;	
ĺ		·	IBM TDB	
14	25	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:22
İ		CMP and polish\$3 and amine	US-PGPUB;	, ,== ==
		• • • • • •	EPO; JPO;	
1			DERWENT;	
			IBM TDB	
	l	1	<u> </u>	

	- 63	I (our in li in modeless in) and CII and	HCDAT.	2002/07/19 12:22
15	63	(sun.in. li.in. redeker.in) and CU and CMP and polish\$3 and pad	USPAT; US-PGPUB;	2003/07/18 12:22
		CMP and polishes and pad	EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	431105	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:22
1.6	431103	CMP and polish\$3 and pad adn amine	US-PGPUB;	2003/07/18 12:22
•		CMF and porisings and pad adm amine	EPO; JPO;	
			DERWENT;	
			IBM TDB	
17	254533	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:22
1 ′	234333	CMP and polish\$3 and pad adn amine and	US-PGPUB;	2003/07/10 12:22
		organic	EPO; JPO;	
		Organic	DERWENT;	
			IBM TDB	•
18	12132	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:23
10	12132	CMP and polish\$3 and pad adn amine and	US-PGPUB;	2003/07/10 12.23
		organic and wafer	EPO; JPO;	
·		Organic and water	DERWENT;	-
			IBM TDB	
19	13	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:23
1 2 9	13	CMP and polish\$3 and pad and amine and	US-PGPUB;	2003/07/10 12.23
		organic and wafer	EPO; JPO;	
		organic and warer	DERWENT;	
			IBM TDB	
i _	0	"cu cmp polishing pad cleaning".ti.	USPAT:	2002/07/23 07:10
	0	ca comp portsorring pad creaming .cr.	US-PGPUB;	2002/07/23 07:10
			EPO; JPO;	
-			DERWENT;	
	•		IBM TDB	
l _	1	"cu cmp polishing".ti.	USPAT;	2002/06/08 18:28
	-	ca comp portaining .cr.	US-PGPUB;	2002/00/00 10.20
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
<u>-</u>	0	cu near3 cmp near3 polishing near3 pad near3	USPAT;	2002/08/05 14:02
		cleaning	US-PGPUB;	2002/00/03 11.02
		010419	EPO; JPO;	
		·	DERWENT;	
			IBM TDB	
_	5	sun.in. & li.in. & redeker.in.	USPAT;	2002/06/08 18:35
	_		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	"REMOVING TONER FROM PRINTED MATERIAL".ti.	USPAT;	2002/06/08 18:35
			US-PGPUB;	
			EPO; JPO;	.
			DERWENT;	
			IBM TDB	,
-	0	"REMOVING TONER FROM PRINTED MATERIAL"	USPAT;	2002/06/08 18:35
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	28881	(amine amide) and ("ph 5" "ph 6" "ph 7" "ph	USPAT;	2002/07/23 07:43
		8" "ph 9" "ph 9" "ph 10" "ph 11" "ph 12")	US-PGPUB;	
		and organic and (acid base)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	4278	((amine amide) and ("ph 5" "ph 6" "ph 7" "ph	USPAT;	2002/07/23 07:19
	,	8" "ph 9" "ph 9" "ph 10" "ph 11" "ph 12")	US-PGPUB;	, ,
		and organic and (acid base)) and	EPO; JPO;	
		ethylenediamine and (phosphoric acetic	DERWENT;	
		sulfuric potassium sodium ammonium) near5	IBM_TDB	
L		(acid hydroxide) and (DI dionized water)		

	10	(((amine amide) and ("ph 5" "ph 6" "ph 7" "ph 8" "ph 9" "ph 9" "ph 10" "ph 11" "ph 12") and organic and (acid base)) and ethylenediamine and (phosphoric acetic sulfuric potassium sodium ammonium) near5 (acid hydroxide) and (DI dionized water) and (copper cu) and (cmp "chemical mechanical polishing")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/23 07:21
-	12	l	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/23 07:48
-	11	"163582"	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/23 07:49
-	5	"359141"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/23 07:51
-	53	"46353"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/23 07:53
-	0	"99/46353"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/23 07:53
-		99/46353	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/23 07:53
-	0.	(copper cu) near3 cmp near3 polishing near3 pad near3 clean\$3	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:22
-	1638	small.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/05 14:22
_	60	small.in. and clean	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/05 14:26
-	8	small.in. and clean and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/05 14:26
-	21	small.in. and clean\$4 and pad	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/05 14:33
1	478	cmp and polish\$4 and method and second\$4 and clean\$4 and pad and (cu copper) and solution	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/05 14:42

-	90	1	USPAT;	2002/08/05 14:44
		clean\$4 and pad and (cu copper) and solution	US-PGPUB;	
		and amin\$4	EPO; JPO;	
			DERWENT;	
			IBM_TDB	((
-	8	small.in. and clean and pad	USPAT;	2002/08/05 16:05
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	21222		IBM_TDB	0000/00/05 16 00
-	21328		USPAT;	2002/08/05 16:23
		acetic	US-PGPUB;	
			EPO; JPO;	
		•	DERWENT;	
	2	small.in. and clean and pad and diamine and	IBM_TDB USPAT;	2002/08/05 16:05
		acetic	US-PGPUB;	2002/08/03 18:05
		acecic	EPO; JPO;	
		,	DERWENT;	
			IBM TDB	
1_	2458	water and cmp and clean and pad \$6amine and	USPAT;	2002/08/05 16:26
	2430	acetic and method and wafer and surface	US-PGPUB;	2002/00/03 10.20
		decere and meetica and water and sarrace	EPO; JPO;	
,			DERWENT;	
			IBM TDB	
_	3216	(diw water) and cmp and clean\$4 and pad	USPAT;	2002/08/05 16:27
	3210	(amine \$6amine) and method and wafer and	US-PGPUB;	2002,00,00 10.27
	,	surface and organic and (cu copper)	EPO; JPO;	
		bulluos and organizo and (ou soppor)	DERWENT;	
			IBM TDB	
_	3216	(diw water) and cmp and clean\$4 and pad	USPAT;	2002/08/05 16:28
	3223	(amine \$6amine) and method and wafer and	US-PGPUB;	2002/00/03 10:20
		surface and organic and (cu copper) and	EPO; JPO;	
		((diw water) and cmp and clean\$4 and pad	DERWENT;	
		(amine \$6amine) and method and wafer and	IBM TDB	
		surface and organic and (cu copper))		
_	1072		USPAT;	2002/08/05 16:29
		(amine) and method and wafer and surface and	US-PGPUB;	,,
		organic and (cu copper) and ((diw water) and	EPO; JPO;	
	ļ	cmp and clean\$4 and pad (amine \$6amine) and	DERWENT;	İ
		method and wafer and surface and organic and	IBM TDB	
		(cu copper)) and clean\$4 near5 pad	_	
-	11	(diw water) and cmp and clean\$4 and pad and	USPAT;	2002/08/05 16:41
		amine and method and wafer and surface and	US-PGPUB;	
		organic and (cu copper) and ((diw water) and	EPO; JPO;	
		cmp and clean\$4 and pad (amine \$6amine)and	DERWENT;	
		method and wafer and surface and organic and	IBM_TDB	
		(cu copper)) and clean\$4 near5 pad		
	3	("5,616,069").PN.	USPAT;	2002/08/05 16:39
			US-PGPUB;	
· .	-	•	EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	
_	11		USPAT;	2002/08/05 16:42
1		wafer and surface and organic and (cu	US-PGPUB;	
		copper) and clean\$4 near5 pad	EPO; JPO;	
			DERWENT;	
		(44	IBM_TDB	0000/05/55
1 -	11	(diw water) and cmp and (hydroxylamine	USPAT;	2002/08/06 06:32
		amine) and method and wafer and surface and	US-PGPUB;	[
	,	organic and (cu copper) and clean\$4 near5	EPO; JPO;	
		pad	DERWENT;	
1_	4.0	(div water UDI waters) and and and and	IBM_TDB	2002/20/25 25 55
1 -	40		USPAT;	2002/08/06 06:55
1		and wafer and surface and RPM and (rate ml/min delivery) and rins\$4 and (condition	US-PGPUB;	
İ		clean\$4) near5 pad	EPO; JPO;	
		creanyr, nears pau	DERWENT;	
L		<u> </u>	IBM TDB	1

	11	(diw water "DI water") and cmp and method	USPAT;	2002/08/06 06:57
		and wafer and surface and RPM and (rate	US-PGPUB;	
		ml/min delivery) and rins\$4 and (condition	EPO; JPO;	
		clean\$4) near5 pad and ml/min	DERWENT;	
	1 ,,	(discontant UDT contant) and amp and mathed	IBM_TDB	2002/08/08 06:36
_	11	(diw water "DI water") and cmp and method and wafer and surface and RPM and (rate	USPAT; US-PGPUB;	2002/08/08 06:36
		ml/min delivery) and rins\$4 and (condition	EPO; JPO;	
-		clean\$4) near5 pad and (ml/min ml/min)	DERWENT;	
		creative, hears pad and (mr/mri mr/mri)	IBM TDB	
_	0	placing near5 polished near5 semiconductor	USPAT;	2002/08/08 06:37
		near5 substrate near5 scrubber and li.in.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		,	IBM TDB	·
-	0	placing near5 polished near5 semiconductor	USPAT;	2002/08/08 06:38
		near5 substrate near5 scrubber	US-PGPUB;	• 1
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	19821	rincoln delarios.in. semiconductor and clean	USPAT;	2002/08/08 06:39
		and substrate	US-PGPUB;	
		·	EPO; JPO;	
].		DERWENT;	
		l.,,,,,.	IBM_TDB	
_	0	rincoln and delarios.in. and semiconductor	USPAT;	2002/08/08 06:39
	1	and clean and substrate	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	8	delarios.in. and semiconductor and clean and	IBM_TDB USPAT;	2002/08/08 07:44
_	•	substrate	US-PGPUB;	2002/08/08 07:44
		Bubbciace	EPO; JPO;	
			DERWENT;	
	1	·	IBM TDB	·
_	2	"6352595"	USPAT;	2002/08/08 08:16
			US-PGPUB;	' '
			EPO; JPO;	
	j		DERWENT;	
			IBM_TDB	
-	2	("6,280,299").PN.	USPAT;	2002/08/08 08:17
			US-PGPUB;	
			EPO; JPO;	
		,	DERWENT;	
		(114 - 22 - 244 1)	IBM_TDB	
_	2	("6,220,941").PN.	USPAT;	2002/08/08 08:17
			US-PGPUB;	
	-		EPO; JPO;	
			DERWENT;	·
_	2	("6242079").PN.	IBM_TDB USPAT;	2002/08/08 13:58
	2	(QZ-120/3).FN.	US-PGPUB;	2002/00/00 13:58
			EPO; JPO;	·
			DERWENT;	
		•	IBM TDB	
_	0	(""aspect ratio" and copper and etch and	USPAT;	2002/08/08 13:59
		adhesion and promotion").PN.	US-PGPUB;	,,,
		• • • • • • • • • • • • • • • • • • • •	EPO; JPO;	, [
			DERWENT;	,
			IBM_TDB	
-	18		USPAT;	2002/08/08 14:00
		adhesion and promotion	US-PGPUB;	
			EPO; JPO;	
		· · · · · · · · · · · · · · · · · · ·	DERWENT;	
·			IBM_TDB	
- ,	17	, <u> </u>	USPAT;	2002/08/08 14:00
		adhesion and promotion	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		<u> </u>	IBM_TDB	

### adhesion and promotion and immersion ### adhesion and promotion and immersion ### ("3889753") or ("4090563") or ("4541945")		·			
Comparison	-	6	"aspect ratio" and copper and etch and adhesion and promotion and immersion		2002/08/08 14:01
Or ("4954142") or ("5084071") or ("5225034") US-PGPUB; Or ("5645682") or ("564562") or ("5567950") or ("564562") or ("564562") or ("5961950") DERMENT; DERMENT; Or ("6031993") or ("4030531") or ("4581945") Or ("4954142") or ("4030531") or ("4581945") Or ("4581942") or ("4581942") or ("564562") or ("564662")				DERWENT;	
or ("\$64582") or ("\$562769") or ("\$509970") or ("\$6035993") or ("\$5030280").PN. 0 (("\$8989753") or ("\$4905631").PN. or ("\$4934142") or ("\$4905631") or ("\$514323") or ("\$4954142") or ("\$4905631") or ("\$525034") or ("\$1403070") or ("\$5179226") or ("\$981454") or ("\$989753") or ("\$179226") or ("\$981454") or ("\$98142") or ("\$360200").PN. or ("\$340370") or ("\$5478436") or ("\$527623") or ("\$645682") or ("\$567699") or ("\$5981454") or ("\$645682") or ("\$5676769") or ("\$559970") or ("\$636868") or ("\$5676769") or ("\$559970") or ("\$6376600") or ("\$5981454") or ("\$63368") - 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	-	48		1	2002/08/15 07:23
0 (("4889783") or ("4990563") or ("4541945") or ("4954142") or ("5486462") or ("5478436") or ("55879226") or ("55879226") or ("55879226") or ("56876508") or ("56879226") or ("5981454") or ("6033993") or ("5830260")]. PN. 17 (("3889753") or ("4990563") or ("4591424") or ("5454662") or ("5478436") or ("4551426") or ("5546562") or ("55879226") or ("5225034") or ("5645622") or ("5645622") or ("5645622") or ("56879226") or ("5981454") or ("5784070") or ("5876508") or ("4881264") or ("5876508") or ("4881264") or ("5876508") or ("4881264") or ("5876508") o			or ("5645682") or ("5662769") or ("5509970") or ("5876508") or ("5879226") or ("5981454")	DERWENT;	
or ("\$876508") or ("\$879226") or ("\$5981454") or ("6033993") or ("4090563") or ("4541945") or ("4954142") or ("504071") or ("5525034") or ("5436362") or ("5509970") or ("5645682") or ("5879226") or ("5509970") or ("6033993") or ("4090563") or ("4541945") or ("6033997") or ("\$636260")).PN. 1 ((("3889753") or ("4090563") or ("4541945") or ("6033997") or ("5476436") or ("5225034") or ("4954142") or ("504071") or ("5225034") or ("5436307") or ("5476436") or ("5527042") or ("5436630") or ("56769") or ("5509970") or ("5645662") or ("56769") or ("5509970") or ("563369") or ("5879226")).PN.) and (amine amide) and organic and pad and surface and clean or "09/163368" - 8 "163368" - 8 "163368" - 9 ("5,981,454").PN. - 10 ("6,280,299").PN. - 11 ("6,280,299").PN. - 12 ("6,280,299").PN. - 13 13	-	0	(("3889753") or ("4090563") or ("4541945") or ("4954142") or ("5084071") or ("5225034") or ("5340370") or ("5478436") or ("5527423")	US-PGPUB	2002/08/15 07:24
or ("5540370") or ("55478436") or ("5527423") or ("56476508") or ("56976508") or ("550970") or ("550970") or ("56976508") or ("5897226") or ("550970") or ("6033939") or ("8303200"), INN. 1 ((("3889753") or ("4090563") or ("5225034") or ("4540370") or ("45478436") or ("5225034") or ("5225034") or ("554970") or ("5549762") or ("5569760") or ("5569760") or ("5569760") or ("5569760") or ("56376508") or ("5633620"), INN.) and (amine amide) and organic and pad and surface and clean organic and pad and surface and clean organic and pad and surface and clean organic and amine and wafer and complex or and complex organic and amine and wafer and c	-	17	or ("5876508") or ("5879226") or ("5981454") or ("6033993") or ("5830280")).PN.	USPAT	2002/08/15 14:41
Or ("4954142") or ("5084071") or ("5225034") US-PGPUB; or ("5545682") or ("5647682") or ("55478436") or ("5509970") or ("5309970") or ("5809970") or ("5809970") or ("5809970") or ("5809870") or ("5			or ("5340370") or ("5478436") or ("5527423") or ("5645682") or ("5662769") or ("5509970") or ("5876508") or ("5879226") or ("5981454")		
Camine amide) and organic and pad and surface and clean USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;		1	or ("4954142") or ("5084071") or ("5225034") or ("5340370") or ("5478436") or ("5527423") or ("5645682") or ("5662769") or ("5509970") or ("5876508") or ("5879226") or ("5981454")	US-PGPUB; EPO; JPO; DERWENT;	2002/08/15 07:26
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DE			(amine amide) and organic and pad and surface and clean		0000/00/05 14 45
- 8 "163368" USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; -		"09/163368"	US-PGPUB; EPO; JPO; DERWENT;	2002/08/15 14:45	
Cu and cmp and ph near2 ("8" "11") and polish and clean composition and organic and amine and wafer and complex Cu and cmp and ph near2 ("8" "11") and polish and clean composition and organic and amine and wafer and complex Cu and cmp and ph near2 ("8" "11") and polish and clean composition and organic and amine and wafer and complex Cu and cmp and ph near2 ("8" "11") and polish and clean composition and organic and amine and wafer and complex Cu and cmp and ph near2 ("8" "11") and polish and clean and complex Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and organic and amine and wafer and complex Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and organic and amine and wafer and complex Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and organic and amine and wafer and complex Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and complex Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and complex Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and uspar; Cu and cmp and ph near2 ("8" "11") and polish and organic uspar; Cu and cmp and ph near	-	8	"163368"	USPAT; US-PGPUB; EPO; JPO;	2002/08/15 14:46
- 2 ("6,280,299").PN. SPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB;	-	2	("5,981,454").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/14 16:06
- 3223 cu and cmp and ph and polish and clean composition and organic and amine and wafer and complex - 3131 cu and cmp and ph near2 ("8" "11") and polish and clean composition and organic and amine and wafer and complex - 8 cu and cmp and ph near2 ("8" "11") and polish and clean and complex - 8 cu and cmp and ph near2 ("8" "11") and polish and clean and composition and organic and amine and wafer and complex - 8 polish\$3 near3 pad near10 clean\$3 - 891 polish\$3 near3 pad near10 clean\$3 - 891 polish\$3 near3 pad near10 clean\$3 - 891 polish\$3 near3 pad near10 clean\$3 - 891 polish\$3 near3 pad near10 clean\$3 - 891 polish\$3 near3 pad near10 clean\$3 - 891 polish\$3 near3 pad near10 clean\$3 - 891 polish\$3 near3 pad near10 clean\$3 - 891 polish\$3 near3 pad near10 clean\$3	-	2	("6,280,299").PN.	USPAT; US-PGPUB; EPO; JPO;	2003/07/16 06:45
- 3131 cu and cmp and ph near2 ("8" "11") and polish and clean composition and organic and amine and wafer and complex - 8 cu and cmp and ph near2 ("8" "11") and polish and clean and composition and organic and amine and wafer and complex - 891 polish\$3 near3 pad near10 clean\$3 IBM_TDB	-	3223	composition and organic and amine and wafer	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/16 06:47
8 cu and cmp and ph near2 ("8" "11") and polish and clean and composition and organic and amine and wafer and complex 9 polish\$3 near3 pad near10 clean\$3 1BM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	-	3131	polish and clean composition and organic	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/16 06:48
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	-	8	polish and clean and composition and	IBM_TDB USPAT; US-PGPUB;	2003/07/16 06:54
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